ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This level	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1					Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and M	ials and Mfg Information			
upplier Inform										, , , , , , , , , , , , , , , , , , , ,		<u> </u>			
Company name*			Company unique ID			Ţ	Unique ID Authority				Response Date*				
nsemi											2024-09-22				
Contact Name			Title - Contact			F	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
uthorized Represe	ntative*	Title - Representative			F	Phone - Representative*				Email - Representative*					
Product-Env-Stewa	rds	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
Requeste	r Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufa		Manufacturing Site	Weight*		UOM	Unit Type		
		NCV8154MW120280 Dual 300 mA, Lov TBG		ow IQ, LDO, wettable	flanks	s 2024-09-22 MY1		MY1	2	23.85	mg	Each			
Ianufacturing l	Proccess Information	1													
Terminal Plating / Grid Array Material Te			Cerminal Base Alloy J-STD-020 MSI		J-STD-020 MSL Rati	ng	Peak Process Body Temperature Max		re Max Time at Peak	Temperat	ure Num	ber of Reflow Cyc	les		
Matte Tin (Sn) - annealed			CU Alloy 1		1		260 C		30	secon	ds 3				
omments															
vel 1 - maximum ti	ime at peak temperature o	during sol	dering is 10-3	0 seconds											
or more informatio	on regarding material con	nposition r	please refer to	page 3					· · · · · · · · · · · · · · · · · · ·						

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.01	mg	Supplier	Silicon (Si)	7440-21-3		1.01	mg
Die Attach	0.12	mg	Supplier	Silver (Ag)	7440-22-4		0.102	mg
			Supplier	Acrylic resins	Proprietary Data		0.018	mg
Lead Frame	7.06	mg	Supplier	Tin (Sn)	7440-31-5		0.0176	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0155	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0176	mg
			Supplier	Copper (Cu)	7440-50-8		7.0092	mg
Lead Frame plating	0.14	mg	Supplier	Silver (Ag)	7440-22-4		0.14	mg
Mold Compound-Black	14.2			Epoxy resin	proprietary data		0.6674	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.42	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0142	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.431	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.6674	mg
Plating	1.1	mg	Supplier	Tin (Sn)	7440-31-5		1.1	mg
Wire Bond - Au	0.22	mg	Supplier	Gold (Au)	7440-57-5		0.22	mg